# **Special Events**

#### **Exhibition**

In the course of the congress, an exhibition will take place in the centrally situated Foyer of the Congress Centrum Amberg, accompanying to the lecture program. Congress participants obtain the opportunity to present their products, manufacturing solutions, and range of services in the field of the mechatronic integrated devices (MID) to the international expert audience of manufacturers and users. For the necessary application (until May 15th, 2023) and further information, please contact the congress office.

#### **General Meeting**

In advance of the Congress a general meeting of the Research Association 3-D MID e.V. takes place on Tuesday June 20<sup>th</sup> from 4.00 p.m. to 6.30 p.m. After the general meeting a reception with the members and the speakers of the congress is offered starting 7.00 p.m. in the Congress Centrum Amberg. Further information will be provided soon.

#### MID Advancement Award 2023 / Best Paper Award

To award an outstanding development work in the area of the MID technology, the Research Association 3-D MID e.V. confers the MID Advancement Award 2023 in the framework of the congress. Additionally, the best scientific congress contribution will be honored with the Best Paper Award.

#### **Evening Event**

Following the lecture program, networking including dinner takes place in the evening of June 21<sup>st</sup>, 2023. The congress center has a beautiful outside area where a buffet with local specialities and drinks are offered.

#### **Technical Tour**

In extension to the conference program, a Technical Tour to SIEMENS in Amberg is offered on Wednesday afternoon, June 22<sup>nd</sup>, 2023. The plant in Amberg is a pilot project and shows the complete program of Industry 4.0, energy efficiency and sustainability possibilities. Registration via the online registration tool (admission fee is 70,- € for the tour and dinner) is necessary.

#### Liability

The congress organization is only authorized to act as an agent and will not be liable for any loss, accident, damage or injury to persons or property, irrespective of the cause. The liability of persons and companies commissioned with the organization will remain unaffected hereby. The guest participates in all tours and events at his / her own risk. Verbal agreements will not be binding, unless they are confirmed in writing. Sole place of jurisdiction is Erlangen, applicable is German law. The decisive date in all cases is that on which incoming mail is stamped by the congress organization in Erlangen. Program changes are reserved.

## **General Information**

#### **Congress Venue**

The conference will take place at the Congress Centrum in Amberg. The airports of Frankfurt a. M. and Nuremberg are reachable within about an hour by train or car. From the railway station, you can reach the Congress Centrum by taxi (about 1 km) or on foot (through the wonderful 'Center', approx. 10 walking minutes).

#### **Congress Language**

The conference language is English. A simultaneous translation will not be provided.

#### **Opening Hours of the Conference Office**

Tuesday, June 20<sup>th</sup> 1.30 p.m. – 9.30 p.m. Wednesday, June 21<sup>st</sup> 8.30 a.m. – 6.00 p.m. Thursday, June 22<sup>nd</sup> 9.00 a.m. – 4.00 p.m.

#### Registration

After registering via the online registration tool, the participation can take place. The registration tool can be found at <a href="https://www.3d-mid.de/en/mid-congress/">www.3d-mid.de/en/mid-congress/</a>

#### **Participation Fees and Service**

The participation fee has to be paid on receipt of the invoice to the account as indicated. It includes the attendance at the congress and the exhibition, the conference proceedings as well as the lunches, beverages during breaks and the evening event. If the payment of the congress fee is not received before the beginning of the congress, a copy of the bank transfer is required.

transfer to required.		
Registration	before May 31 <sup>th</sup>	after May 31 <sup>th</sup>
Standard:	800€	960,-€
Members 3-D MID e.V.:	600€	720,-€
Speakers and University Memb	er: 350€	500,-€
Exempt from VAT according to § 4, Nr. 22a UStG		

**Cancellations** can only be accepted in written form. The following processing fees will be charged:

- before May 31<sup>th</sup>, 2023: 50€, the conference proceedings will not be sent.
- after May 31th, 2023: total fee, the conference proceedings will be sent.

#### **Organization Committee**

- Prof. J. Franke University of Erlangen-Nuremberg, FAPS, GER
- Dr. Andreas Reinhard SEHO, GER
- Prof. Zimmermann Hahn Schickard e.V. GER
- Dr. A. Poitinger 2E mechatronic GmbH & Co. KG, GER
- R. Süß-Wolf Research Association 3-D MID e. V., GER
- S. Landvogt Research Association 3-D MID e. V., GER

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# **INVITATION**



#### 15<sup>th</sup> International Congress

# Mechatronic Integration Discourse

### Congress Centrum Amberg June 21<sup>st</sup> – 22<sup>nd</sup>, 2023

#### organized by

Research Association

Mechatronic Integrated Devices 3-D MID e.V

#### in cooperation with

University of Erlangen-Nuremberg Institute for Factory Automation and Production Systems – FAPS







# **MID – Mechatronic Integrated Devices**

#### **Functional Integration by MID**

Due to a direct application of conductor tracks and functional structures on randomly shaped substrates, the MID technology (Molded Interconnect Devices / Mechatronic Integrated Devices) enables the production of highly integrated mechatronic products. The varied possibilities for combining electrical / electronical, mechanical, optical, thermal and fluidic functions in one unit offer enormous potential to meet the increasing requirements regarding miniaturization and function density, reliability and costs in the various fields of application.

#### **MID Technology ready for the Future**

With the Internet of Things (IoT) and growing demand for digitalization and networking everywhere the world of technology faces new challenges. Electronic needs to be integrated in nearly every devicesmall, flexible, smart and reliable. MID redefined as Mechatronic Intergrated Device reflects the market requirement. Breaking the boundaries to offer an holistic technology approach is the aim of MID in the future.

With printing and flexible technologies in production and application new solutions will be made possible with MID. The MID Congress 2023 is the starting point for a new understanding. Be part of this experience.

# Latest Technology Developments from both an Industrial and a Scientific Perspective

Advanced mechatronic systems are characterized by the intelligent integration of different functions in miniaturized installation space and use the latest developments in materials, manufacturing processes as well as production technology. The extensive conference program provides an excellent overview of the current state of the art by target-group-oriented sessions:

- Potentials through MID for various fields of application
- Presentations of innovative MID applications
- New application potentials through printed electronics
- Latest developments in the field of MID materials
- Additive manufacturing and MID prototyping
   Methodology of development and testing

#### MID 2023: Platform for Experts and Beginners

The international conference has established itself as a worldwide recognized forum for the MID technology:

- Lectures from manufacturers, users and research institutes
- Intensive exchange of information and experience
- Direct information at the accompanying exhibition
- Attractive social program for informal contacting
- Technical Tour to SIEMENS AG, Amberg